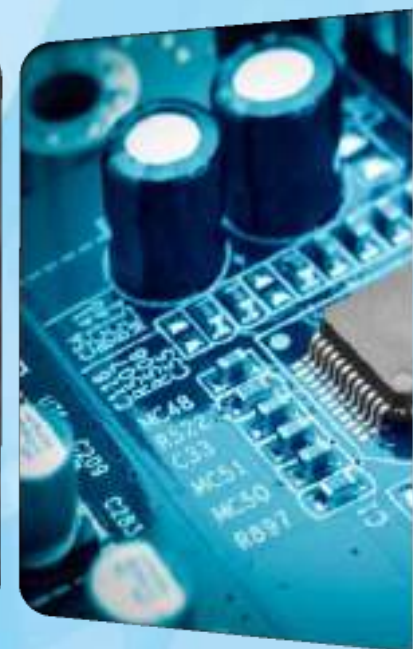




IEEE 開放取用與 2023 投稿優惠詳解

何丹丹，IEEE大中華區客戶與資訊經理

杜欣穎 Cindy Tu，Hinton產品&行銷經理



主要内容

- 如何提高自己科研的可見度和影響力
- 在IEEE期刊發表開放取用文章的益處
- IEEE 2023 OA 投稿優惠詳解與實踐流程

關於 IEEE

- IEEE是全球最大的技術學會，會員遍佈世界160多個國家和地區，會員人數也已超過了40萬
- 作為一個非營利的組織，IEEE始終肩負“驅動技術創新，為人類謀福祉”這一使命
- 核心活動
 - 會員組織
 - 會議組織
 - 標準開發
 - 科技出版（期刊、會議錄、標準、電子圖書以及線上課程等資源）



如何提高自己科研的可見度和影響力

問題提出

發表論文

研究實施與結果收集

完整科研流程應該包含哪些步驟？

研究設計

推廣研究

文獻調研

撰寫論文

在科研全流程提升研究可見度

- 清晰簡潔的標題，突出讀者可能的興趣點
- 精准、標準化的關鍵字
- 建立自己的學術檔案（IEEE Xplore作者頁面, ORCID等）
- 將論文提交給有影響力的學術機構發表
- 參加學術會議/研討會展示研究成果
- 多途徑推廣學術成果
- 以OA形式發表研究成果
- 分享研究相關代碼、資料等相關材料

IEEE Xplore 作者頁面



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Author

Winnie N. Ye  

Also published under: Winnie Ye, W. N. Ye, W. Ye

作者姓名消歧

Affiliation

Department of Electronics

1125 Colonel By Drive

Carleton University, Ottawa, Canada

Publication Topics

integrated optics, diffraction gratings, silicon, elemental semiconductors, optical waveguides, silicon-on-insulator, integrated optoelectronics, optical communication equipment, beam steering, demultiplexing, micro-optics, optical

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Biography

Winnie N. Ye (Senior Member, IEEE) received the B.Eng. degree in electrical engineering from Carleton University, Ottawa, ON, Canada, the M.A.Sc. degree in photonics from the University of Toronto, Toronto, ON, and the Ph.D. degree in photonics from Carleton University. She is currently a Full Professor with the

Publications

52

Citations?

338

Publications by Year



Co-Authors:

Sawsan Abdul-Majid

Alireza Aleali

C. Alonso-Ramos

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名稱

Winnie N. Ye

活動

▼ 受邀職位與傑出貢獻 (1)

Engineering Institute of Canada (EIC): Ottawa, CA-ON, CA

2020-01-01 至 當前 | Fellow EIC
受邀職位

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來源: Winnie N. Ye

▼ 成果 (50)

≡ 排序

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Sensors

2022-08-16 | 期刊文章

DOI: [10.3390/s22166135](https://doi.org/10.3390/s22166135)

投稿人: Daniel Benediković; Qiankun Liu; Alejandro Sánchez-Postigo; Ahmad Atieh; Tom Smy; Pavel Cheben; Winnie N. Ye

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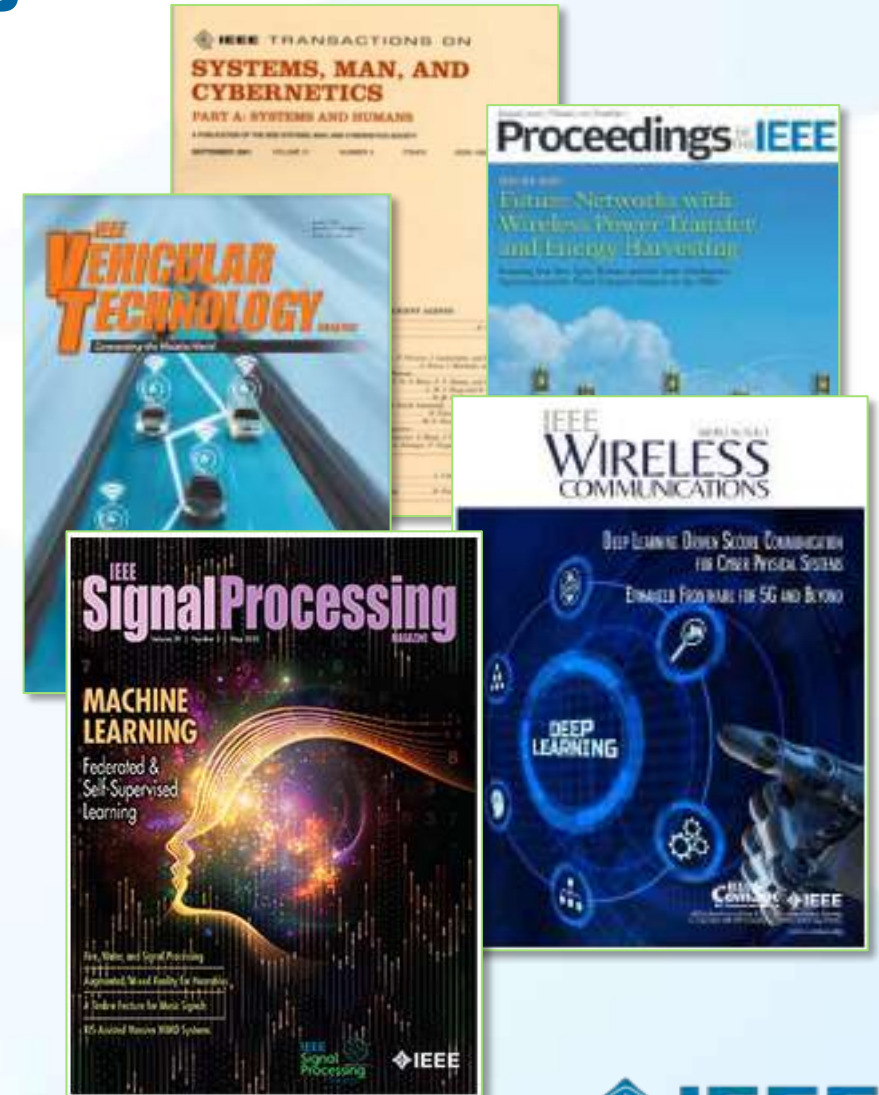
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以預覽文獻形式快速發表經過同行評審的論文，並立即獲得DOI

The screenshot displays the IEEE Xplore website interface. On the left, a sidebar shows search filters with 'Early Access Articles (26,503)' highlighted in a red box. A blue button labeled '預覽文獻' (Preview Literature) is positioned below this filter. The main content area is divided into two sections by a red 'VS' label. The top section, representing the regular publication path, shows a paper published in 'IEEE Transactions on Circuits and Systems I: Regular Papers' (Volume: 69, Issue: 3, March 2022), with the date '07 December 2021' highlighted in a red box. The bottom section, representing the early access path, shows a paper published in 'IEEE Transactions on Circuits and Systems I: Regular Papers (Early Access)', with the date '11 March 2022' highlighted in a red box. Both sections include page numbers and a DOI. A blue box at the bottom right explains that DOI stands for Digital Object Identifier, a unique digital identifier for digital objects.

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Page(s): 83740 - 83750

INSPEC Accession Number: 21012216

Date of Publication: 02 June 2021  DOI: 10.1109/ACCESS.2021.3085404

Electronic ISSN: 2169-3536

Publisher: IEEE

► Funding Agency:



Architecture of the EyeFundusScopeNEO system.



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■ 通過郵件等形式分享學術成果

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A Mobile Tele-Ophthalmology System for Planned and Opportunistic Screening of Diabetic Retinopathy in Primary Care

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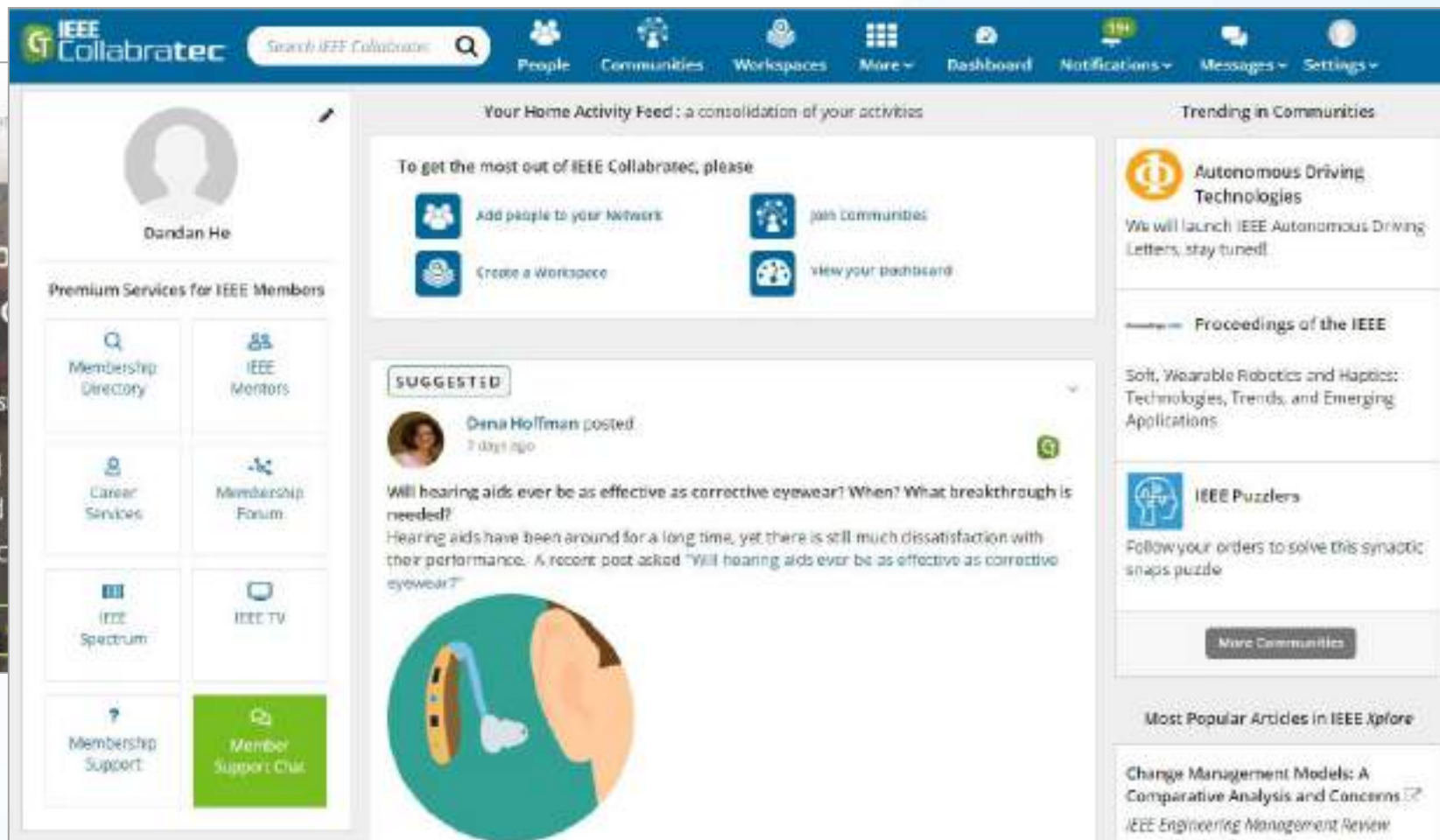
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Article Title	A Mobile Tele-Ophthalmology System for Planned and Opportunistic Screening of Diabetic Retinopathy in Primary Care
Publication Title	IEEE Access
Posted Online Date	2 Jun 2021
Authors	Francisco Nunes; Pedro Madureira; Silvia Rêgo; Cristiana Braga; Rúben Moutinho; Tiago Oliveira; Filipe Soares

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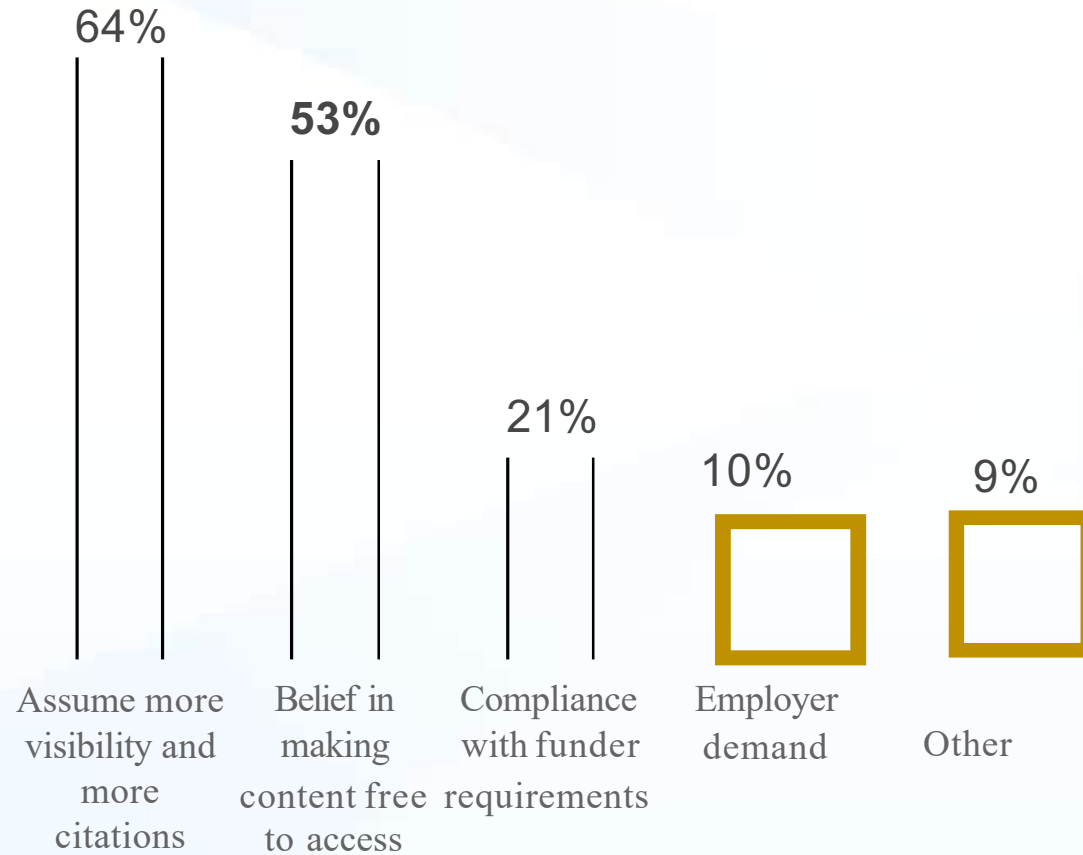
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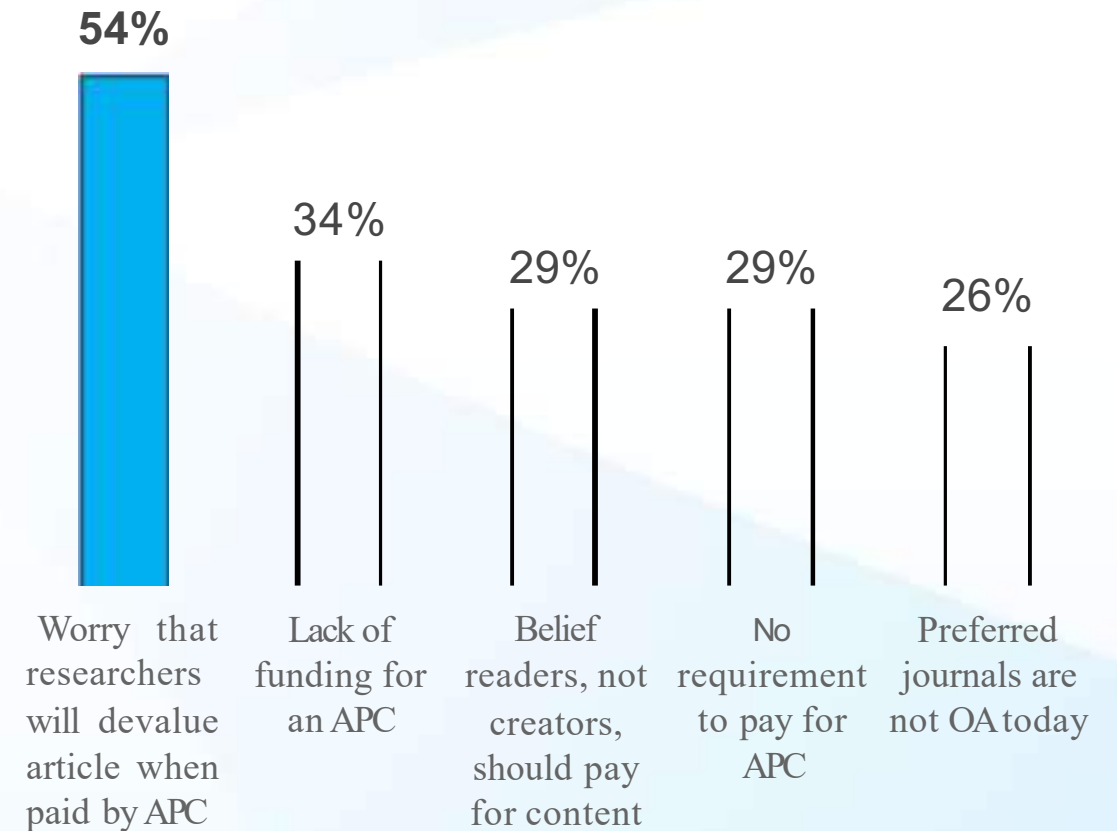
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2021 IEEE作者調查

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Those preferring traditional journals



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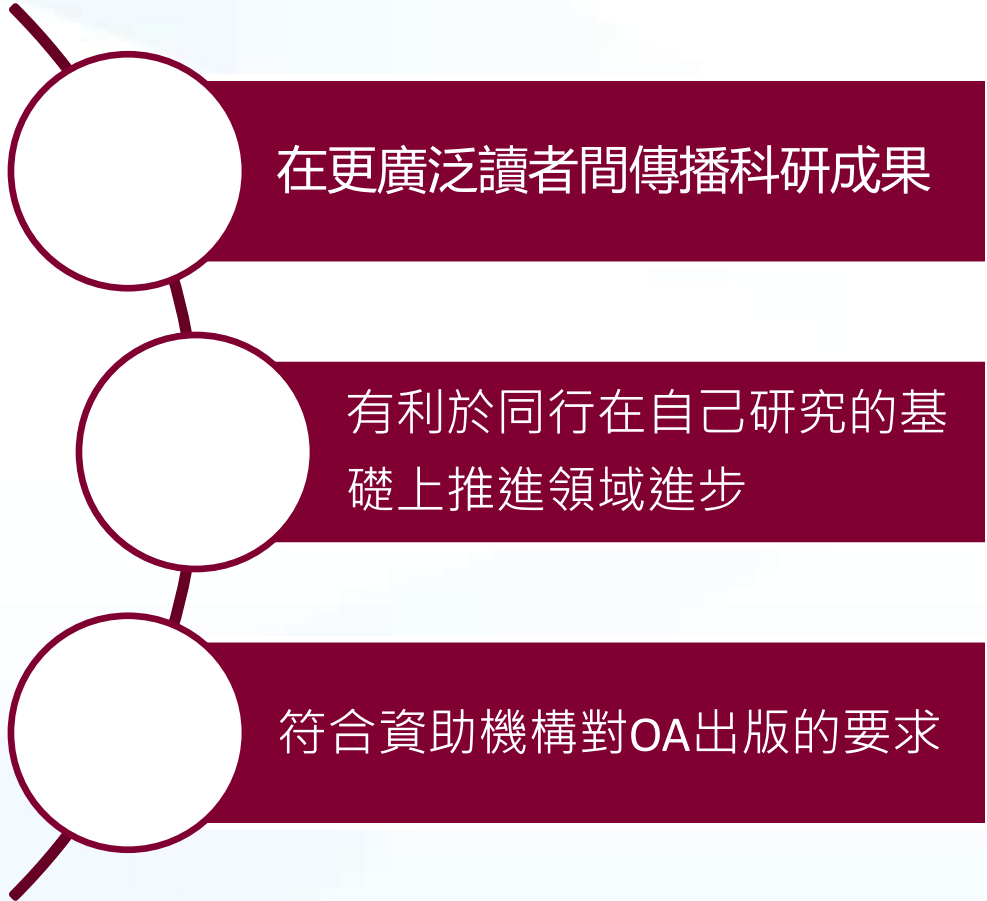
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- IEEE Journal of Translational Engineering in Health and Medicine
- IEEE Open Access Journal of Power and Energy
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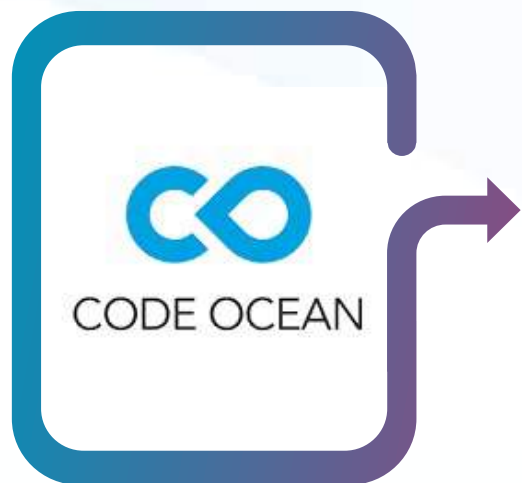
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Index Modulation Based Coordinate Interleaved Orthogonal Design for Secure Communications

Publisher: IEEE

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Burak Ozpoyraz · Ibrahim Yildirim · Ertugrul Basar

All Authors

Code Available

Abstract

In this paper, we propose a physical layer security scheme that exploits a novel index modulation (IM) technique for coordinate interleaved orthogonal designs (CIOD). Utilizing the diversity gain of CIOD transmission, the proposed scheme, named CIOD-IM, provides an improved spectral efficiency by means of IM. In order to provide a satisfactory secrecy rate, we design a particular artificial noise matrix, which does not affect the performance of the legitimate receiver, while deteriorating the performance of the eavesdropper. We derive expressions of the ergodic secrecy rate and the theoretical bit error rate upper bound. In addition, we analyze the case of imperfect channel estimation by taking practical concerns into consideration. It is shown via computer simulations that the proposed scheme outperforms the existing IM-based schemes and might be a candidate for future secure communication systems.

0

Abstract

Document Sections

- I. Introduction
- II. System Model
- III. Performance Analysis
- IV. Simulation Results
- V. Conclusion

Abstract:

In this paper, we propose a physical layer security scheme that exploits a novel index modulation (IM) technique for coordinate interleaved orthogonal designs (CIOD). Utilizing the diversity gain of CIOD transmission, the proposed scheme, named CIOD-IM, provides an improved spectral efficiency by means of IM. In order to provide a satisfactory secrecy rate, we design a particular artificial noise matrix, which does not affect the performance of the legitimate receiver, while deteriorating the performance of the eavesdropper. We derive expressions of the ergodic secrecy rate and the theoretical bit error rate upper bound. In addition, we analyze the case of imperfect channel estimation by taking practical concerns into consideration. It is shown via computer simulations that the proposed scheme outperforms the existing IM-based schemes and might be a candidate for future secure communication systems.

Code & Datasets

[Code](#) [Dataset](#)

This article includes code hosted on Code Ocean, a computational reproducibility platform that allows users to view, modify, run, and download code enclosed with IEEE Xplore articles. RDTG, a Code Ocean user account is required to access functionality in the repository.

Code: [MATLAB Index Modulation Based Coordinate Interleaved Orthogonal Designs](#)

Index Modulation Based Coordinate Interleaved Orthogonal Designs (CIOD-IM) for Secure Communications

1. Introduction

2. System Model

3. Performance Analysis

4. Simulation Results

5. Conclusion

6. Appendix

7. References

8. Biographies

9. Indexing Terms

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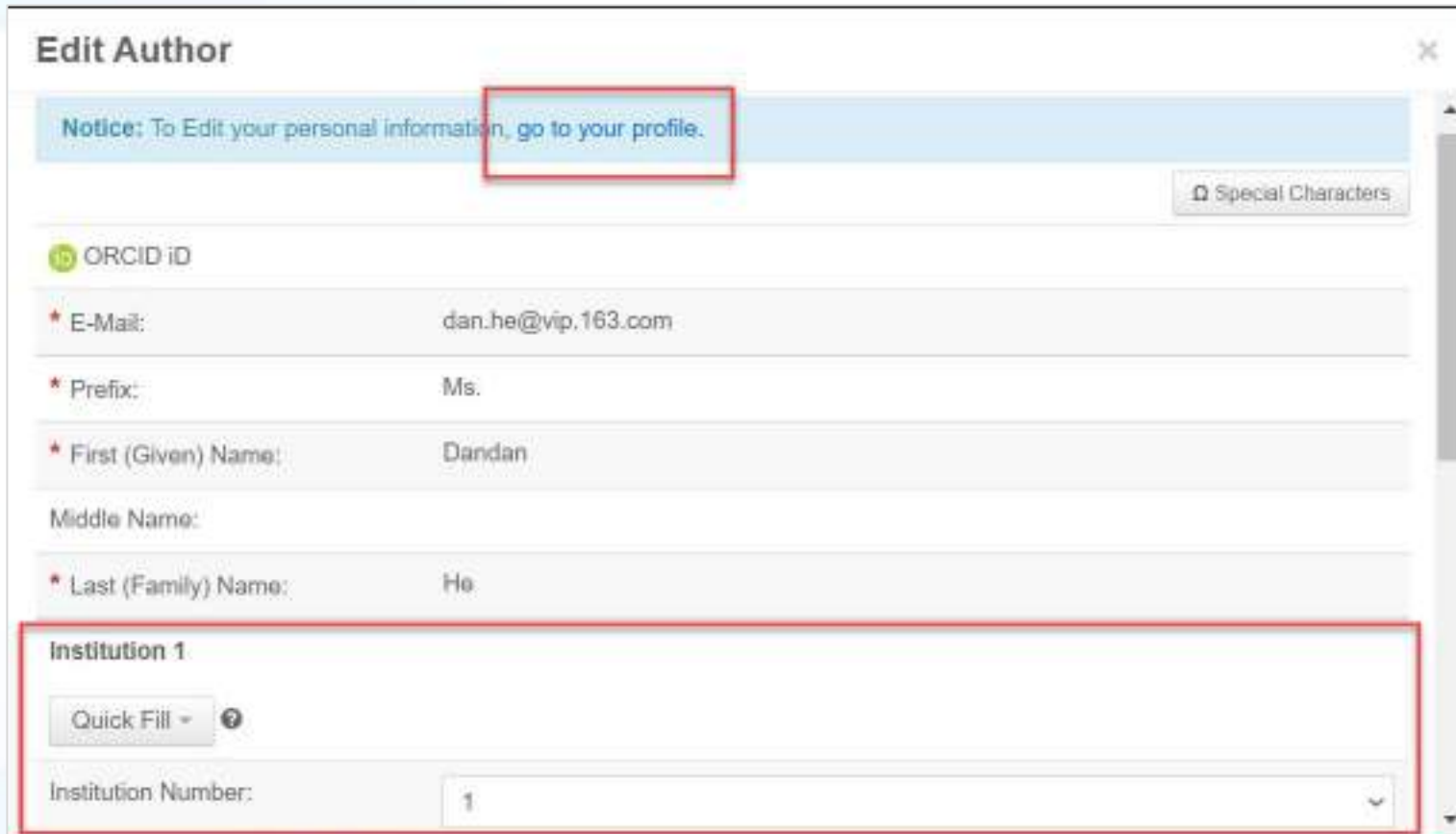
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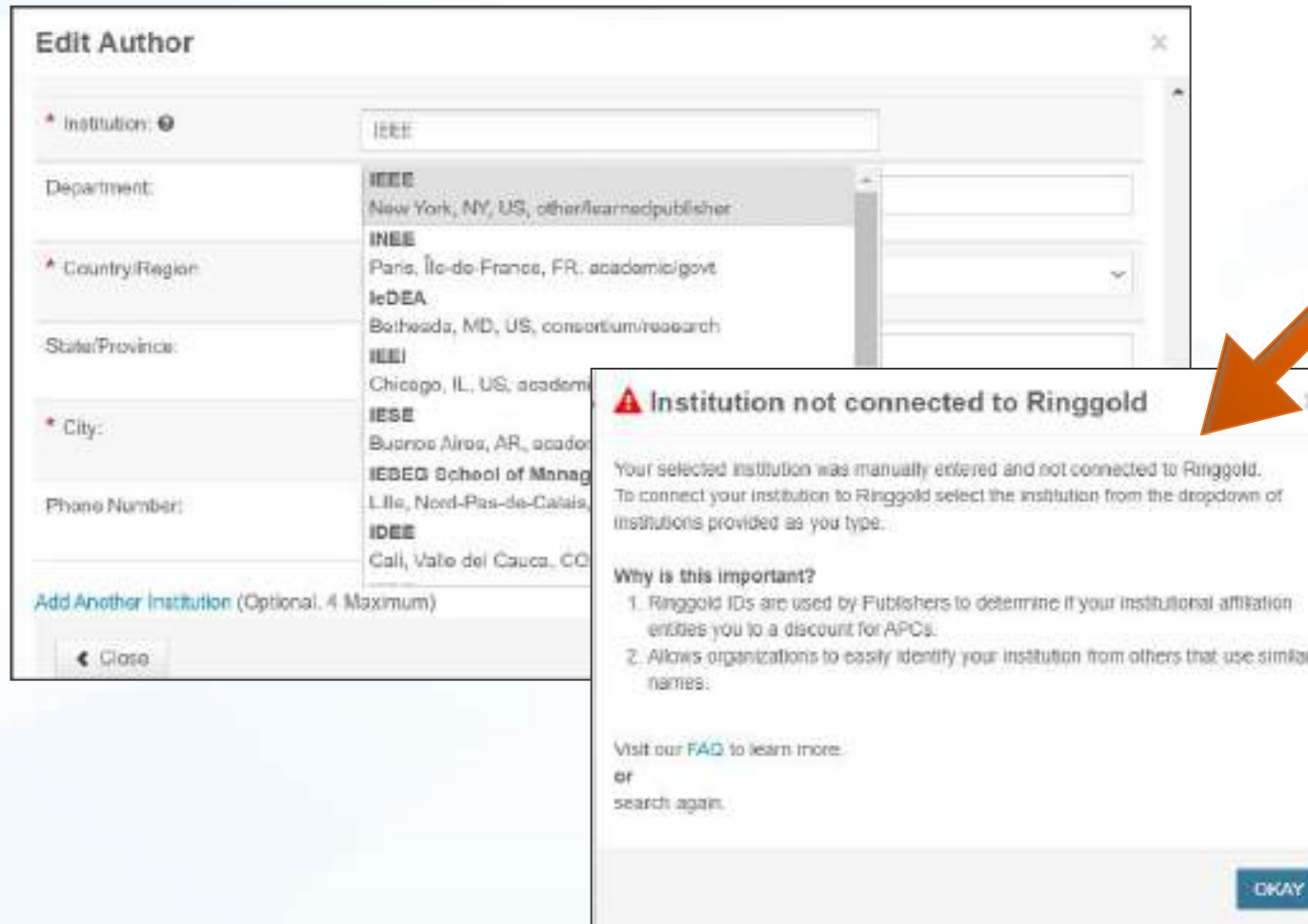
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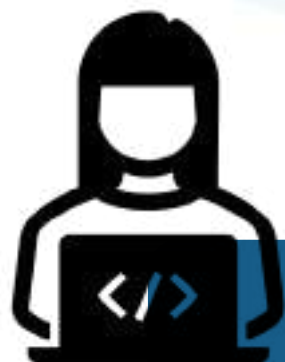


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